

## Common-Drain Dual N-Channel MOSFET

### ■ DESCRIPTION

SMC4270 is the Dual N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology to provide excellent  $R_{DS(ON)}$ . These devices are well suited for high efficiency fast switching applications, low in-line power loss are needed in small outline surface mount package.

### ■ PART NUMBER INFORMATION

**SMC 4270 S6 - TR G**

a	b	c	d	e
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a : Company name.

b : Product Serial number.

c : Package code            S6:SOT-23-6L

d : Handling code            TR:Tape&Reel

e : Green produce code    G:*RoHS Compliant*

### ■ FEATURES

$$V_{DS} = 20V, \quad I_D = 6.7A$$

$$R_{DS(ON)} = 16m\Omega (\text{Typ.}) @ V_{GS} = 4.5V$$

$$R_{DS(ON)} = 17m\Omega (\text{Typ.}) @ V_{GS} = 4.0V$$

$$R_{DS(ON)} = 18m\Omega (\text{Typ.}) @ V_{GS} = 3.2V$$

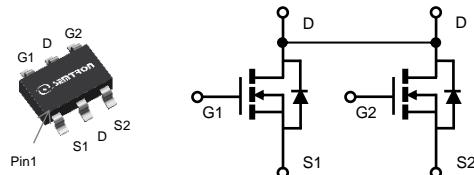
$$R_{DS(ON)} = 20m\Omega (\text{Typ.}) @ V_{GS} = 2.5V$$

$$R_{DS(ON)} = 24m\Omega (\text{Typ.}) @ V_{GS} = 1.8V$$

- ◆ Fast switch
- ◆ High power and current handling capability
- ◆ Exceptional on-resistance

### ■ APPLICATIONS

- ◆ Power Management in Notebook Computer
- ◆ Portable Equipment and Battery Powered.



SOT-23-6L

### ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-Source Voltage	20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current ( $V_{GS}=4.5V$ )	$T_A=25^\circ\text{C}$	A
		$T_A=70^\circ\text{C}$	A
$I_{DM}$	Pulsed Drain Current <sup>A</sup>	26.8	A
$P_D$	Power Dissipation <sup>B</sup>	$T_A=25^\circ\text{C}$	W
		$T_A=70^\circ\text{C}$	W
$T_J$	Operation Junction Temperature	-55/150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55/150	$^\circ\text{C}$

### ■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>B</sup>	$t \leq 10s$	90	$^\circ\text{C}/\text{W}$
	Thermal Resistance Junction to Ambient <sup>BC</sup>	Steady-State	130	

**ELECTRICAL CHARACTERISTICS( $T_A = 25^\circ\text{C}$  Unless otherwise noted)**

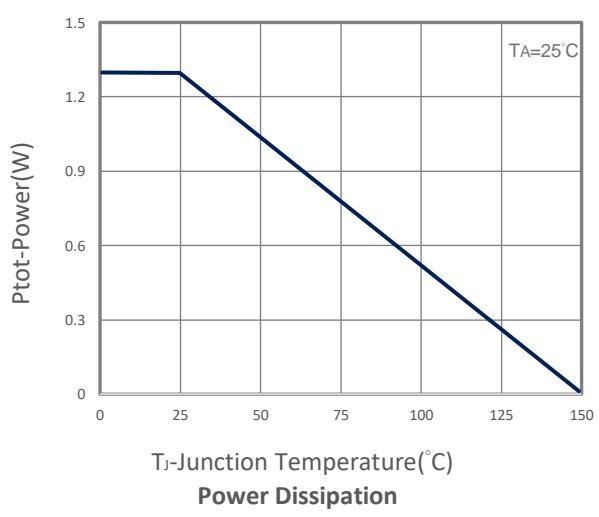
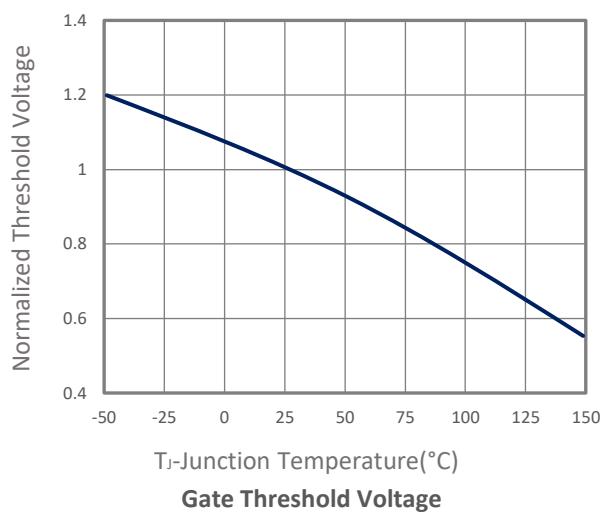
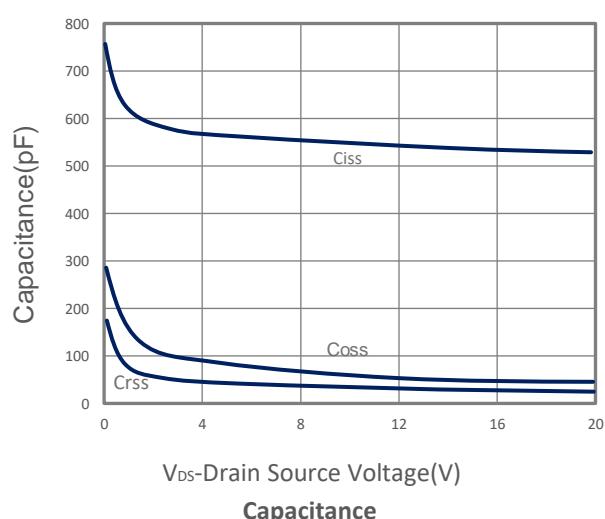
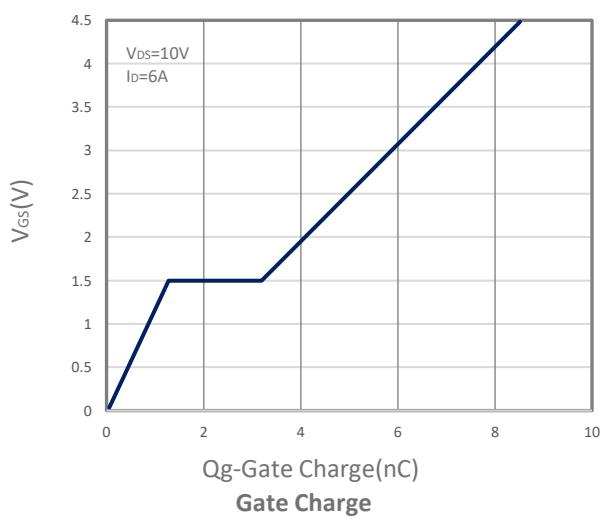
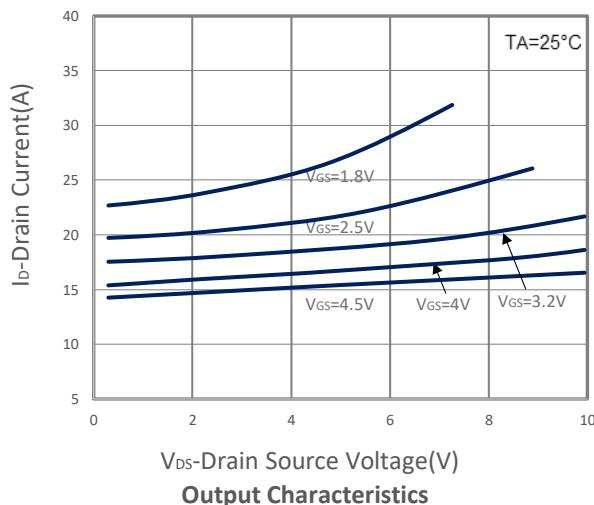
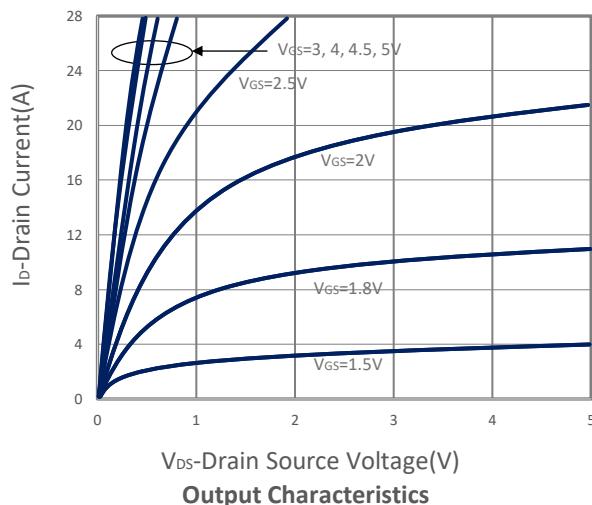
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20			V	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4	0.6	1.0	V	
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			$\pm 100$	nA	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$		1		$\mu\text{A}$	
		$V_{DS}=16\text{V}, V_{GS}=0\text{V}, T_J=75^\circ\text{C}$		10			
$R_{DS(\text{ON})}$	Drain-source On-Resistance	$V_{GS}=4.5\text{V}, I_D=6\text{A}$	16	19		$\text{m}\Omega$	
		$V_{GS}=4.0\text{V}, I_D=5\text{A}$	17	20			
		$V_{GS}=3.2\text{V}, I_D=4\text{A}$	18	21			
		$V_{GS}=2.5\text{V}, I_D=3\text{A}$	20	24			
		$V_{GS}=1.8\text{V}, I_D=2\text{A}$	24	29			
<b>Source-Drain Diode</b>							
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.7	1	V	
$I_S$	Continuous Source Current				3.5	A	
<b>Dynamic Parameters</b>							
$Q_g$	Total Gate Charge	$V_{DS}=10\text{V}, V_{GS}=4.5\text{V}, I_D=6\text{A}$		8.5	11.9	nC	
$Q_{gs}$	Gate-Source Charge			1.4	2		
$Q_{gd}$	Gate-Drain Charge			2.2	3.1		
$C_{iss}$	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		550		pF	
$C_{oss}$	Output Capacitance			65			
$C_{rss}$	Reverse Transfer Capacitance			41			
$t_{d(on)}$	Turn-On Time	$V_{DD}=10\text{V}, V_{GEN}=4.5\text{V}$ $R_G=3\Omega, I_D=1\text{A}$		4.8	9.1	nS	
$t_r$				13.5	25.7		
$t_{d(off)}$	Turn-Off Time			28	53.2		
$t_f$				8.8	16.7		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

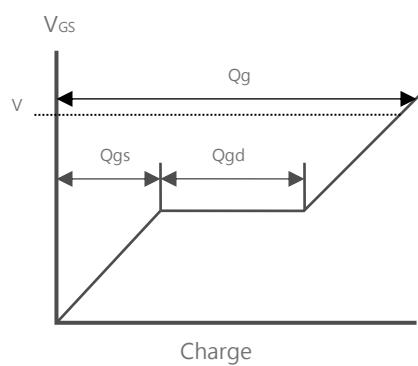
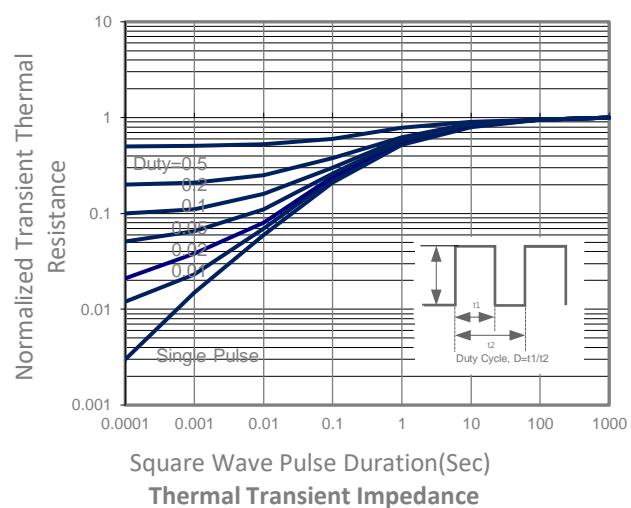
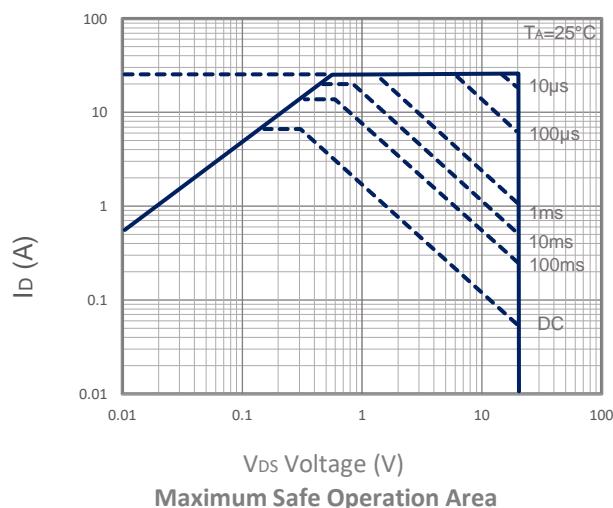
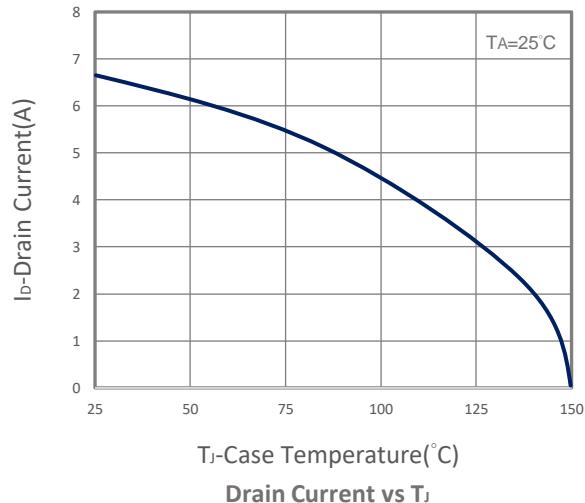
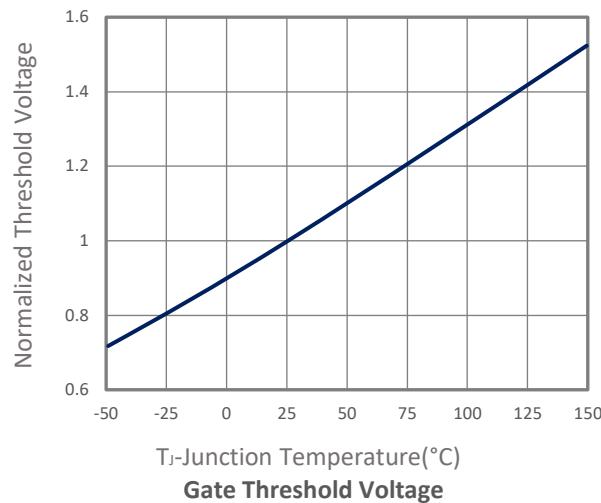
- A. Pulsed width limited by maximum junction temperature,  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- B. The value of  $R_{eJA}$  is measured with the device mounted on 1in2 FR-4 board in a still air environment with maximum junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$  (initial temperature  $T_A=25^\circ\text{C}$ ).
- C.  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using junction-to-case thermal resistance ( $R_{eJC}$ ) is more useful in additional heat sinking is used.

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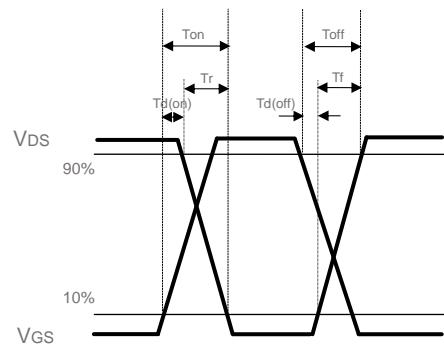
## TYPICAL CHARACTERISTICS



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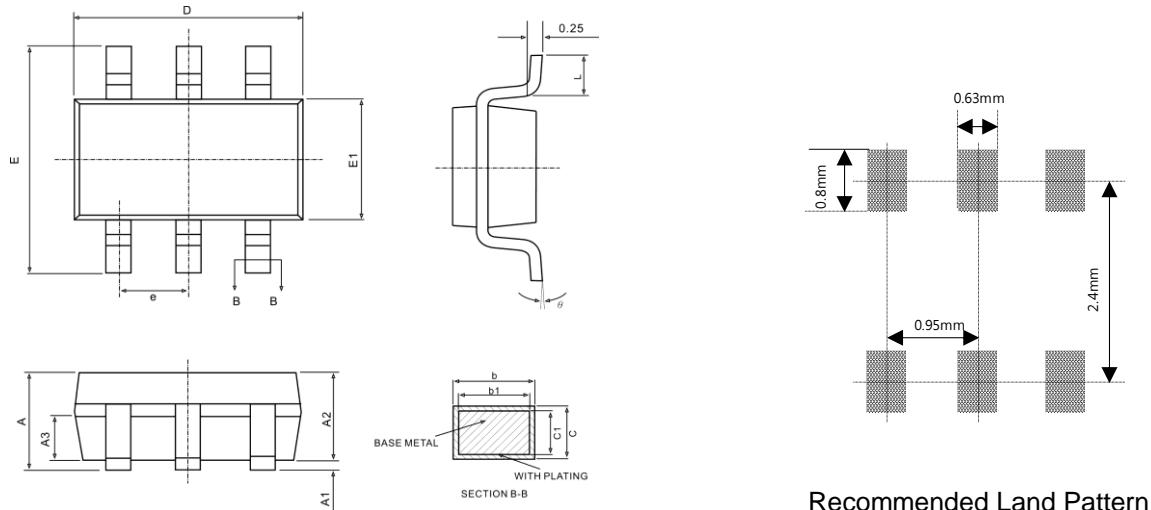


Gate Charge Waveform



Switching Time Waveform

## SOT-23-6L PACKAGE DIMENSIONS



Recommended Land Pattern

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	-	1.300	-	0.051
A1	0.040	0.100	0.002	0.004
A2	1.000	1.200	0.039	0.047
A3	0.550	0.750	0.022	0.030
b	0.340	0.430	0.013	0.017
b1	0.330	0.380	0.013	0.015
c	0.150	0.210	0.006	0.008
c1	0.140	0.160	0.006	0.006
D	2.720	3.120	0.107	0.123
E	2.600	3.000	0.102	0.118
E1	1.400	1.800	0.055	0.071
e	0.950 BSC		0.066 BSC	
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°